

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| 1 | 1779 | (438/612).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:47 |
| 2 | 1 | bond adj pad with copper with 'Al' and 'buffer' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:46 |
| 3 | 11 | 'bond' and 'pad' with copper with 'Al' and 'buffer' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:54 |
| 4 | 284 | (438/48).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:47 |
| 7 | 1722 | (438/614).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 10:35 |
| 8 | 573 | (257/459).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:49 |
| 9 | 1222 | (257/784).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 10:37 |
| 10 | 1209 | (257/786).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:51 |
| 11 | 735 | (257/781-782).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:52 |
| 12 | 1392 | (257/774).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 11:44 |
| 13 | 1 | 'bond pad' with 'copper' with 'Al' and 'buffer' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:55 |
| 14 | 1 | 'bonding pad' with 'copper' with 'Al' and 'buffer' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:56 |
| 15 | 122 | 'bonding pad' with 'Cu' with 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 09:05 |
| 16 | 117 | @ad<=20020109 and 'bonding pad' with 'Cu' with 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 09:01 |

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| 29 | 6 | @ad<=20020109 and cu adj 'bonding pad' with 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 09:03 |
| 30 | 117 | @ad<=20020109 and 'bonding pad' with 'Cu' with 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 09:05 |
| 33 | 1 | | USPAT | 2003/01/23 09:57 |
| 34 | 1 | | USPAT | 2003/01/23 09:57 |
| 35 | 1 | | USPAT | 2003/01/23 09:57 |
| 36 | 1 | | USPAT | 2003/01/23 09:58 |
| 49 | 246 | @ad<=20020109 and 'bonding pad' with 'integrated circuit' and 'Cu' and 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 10:02 |
| 50 | 231 | (257/784).ccls. and @ad<=20020109 and 'Copper' and 'aluminum' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 10:38 |
| - | 2054 | (438/612).ccls. or (438/597).ccls. and @ad<=20020109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:44 |
| - | 337 | ((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and copper and aluminum | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:04 |
| - | 74 | ((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and 'bonding pad' with 'integrated circuit' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 10:01 |
| - | 1 | ((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Cu adj bonding adj pad with 'integrated circuit' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:13 |
| - | 6 | ((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Copper adj bonding adj pad | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:14 |
| - | 1143 | @ad<=20020109 and cu adj 'bonding pad' with 'IMD' or 'intermetal dielectric' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:45 |
| - | 0 | @ad<=20020109 and cu adj 'bonding pad' with 'IMD' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:27 |
| - | 0 | @ad<=20020109 and cu adj 'bonding pad' with 'intermetal dielectric' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:27 |
| - | 6 | @ad<=20020109 and cu adj 'bonding pad' with 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 09:03 |

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| - | 3 | @ad<=20020109 and cu adj 'bonding pad' and 'IMD' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:43 |
| - | 1 | "3942245".PN. | USPAT | 2002/08/21 11:40 |
| - | 1 | "5075965".PN. | USPAT | 2002/08/21 11:40 |
| - | 1 | "5288006".PN. | USPAT | 2002/08/21 11:40 |
| - | 1 | "5376235".PN. | USPAT | 2002/08/21 11:41 |
| - | 1 | "5384284".PN. | USPAT | 2002/08/21 11:41 |
| - | 1 | "5436412".PN. | USPAT | 2002/08/21 11:42 |
| - | 0 | @ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:45 |
| - | 4 | @ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:46 |
| - | 809 | ((228/180.21).CCLS.) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:48 |
| - | 93 | ((228/180.21).CCLS.) and bonding adj pad | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 11:50 |
| - | 9 | ((228/180.21).CCLS.) and bonding adj pad with copper | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 13:32 |
| - | 8 | ((228/180.21).CCLS.) and bond adj pad with copper | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 13:30 |
| - | 0 | ((228/180.21).CCLS.) and bond adj pad with copper with 'Al' adj buffer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/23 08:45 |
| - | 0 | ((228/180.21).CCLS.) and bond adj pad with copper with 'Al' | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 13:31 |
| - | 639 | @ad<=20010119 and bonding adj pad with copper | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 13:36 |
| - | 359 | @ad<=20010119 and bonding adj pad with copper and aluminum | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 13:47 |
| - | 30 | @ad<=20010119 and copper adj bonding adj pad and aluminum | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 13:59 |
| - | 839 | @ad<=20010119 and bonding adj pad and aluminum and buffer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/08/21 14:00 |

4120 "bonding pad" and apparatus

USPAT; 2002/08/21 15:03

US-PGPUB;

EPO; JPO;

DERWENT;

IBM_TDB

3573 ((257/459) or (257/676) or (257/786) or
(275/670) or (257/672)).CCLS.

USPAT; 2002/08/21 15:07

US-PGPUB;

EPO; JPO;

DERWENT;

IBM_TDB